

C2225C334KBRAC TU

Aliases (C2225C334KBRAC7800)

SMD Comm X7R HV, Ceramic, 0.33 uF, 10%, 630 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 2225



Click [here](#) for the 3D model.

Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	2mm +/-0.20mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

General Information	
Series	SMD Comm X7R HV
Style	SMD Chip
Description	SMD, MLCC, High Voltage, Temperature Stable
Features	High Voltage
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	430 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	303 MOhms

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